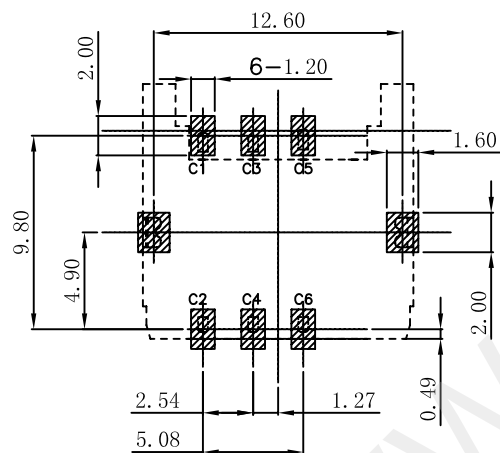
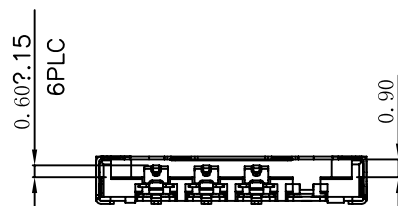
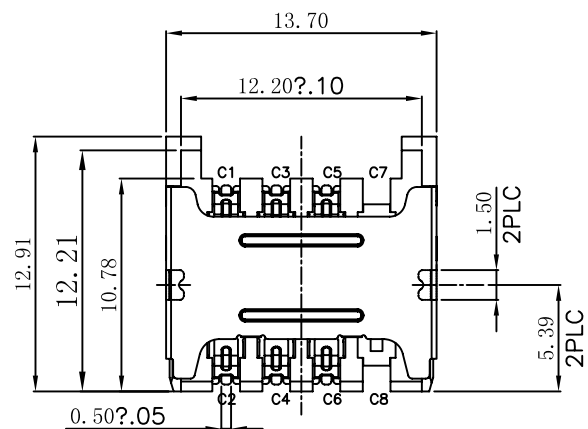
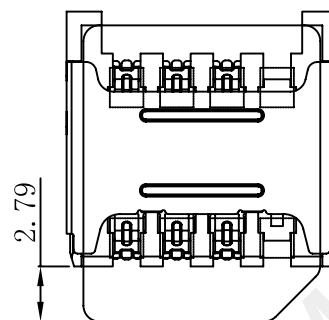
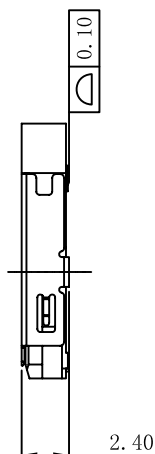
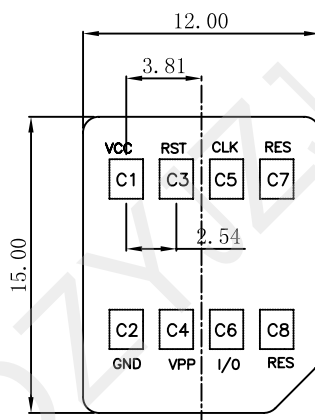




RECOMMENDED PCB LAYOUT (TOP VIEW)
GENERAL TOLERANCES: ±0.05



INSERT CARD



MICRO SIM CARD
芯片面朝下视图

MICRO SIM CARD	
PIN NO.	DESCRIPTION
C1	VCC
C3	RST
C5	CLK
C7	
C2	GND
C4	VPP
C6	I/O
C8	

NOTES:

1) MATERIAL:
HOUSING: LCP UL 94V-0
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL

2) FINISH:

CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATING ON SOLDER TAILS,
WITH ENTIRE CONTACT UNDERPLATED NICKEL
SHELL: NICKEL UNDERPLATED OVERALL,
GOLD FLASH PLATED ON SOLDER TAILS



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TOLERANCE:

X.X ±0.30
X.XX ±0.25
X.XXX ±0.15

X* ±2° X.X* ±0.5°



UNIT: mm [inch]

SCALE: 1:1 SIZE: A4

DRAWN BY:

陈一鸣

DATE:

2014-02-23

PART NAME:

MICRO SIM 6P连桥带挡 2.4H

CHECKED BY:

马跃

DATE:

2014-02-23

PART NO.

HYC278-SIM06-240

APPROVED BY:

邱敏

DATE:

2014-02-23

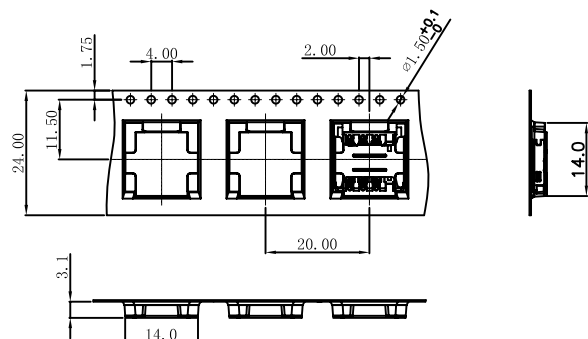
DRAW NO.

HYC-2104301553

SHEET NO.

1 OF 1

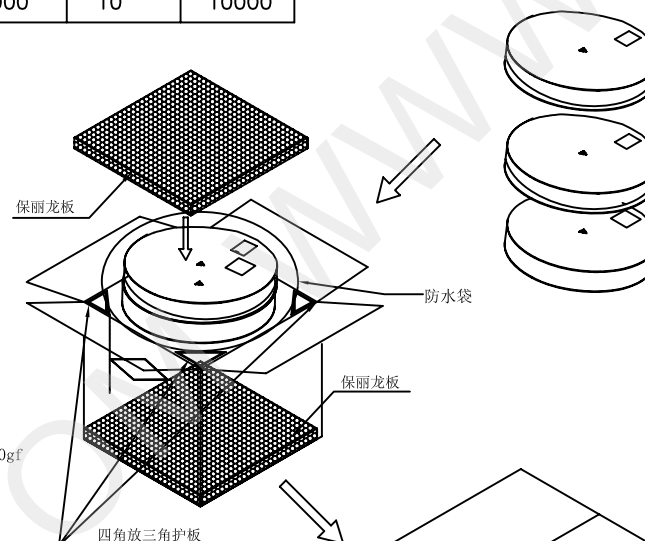
<图一>



<TABLE 1> PACKAGING QUANTITY

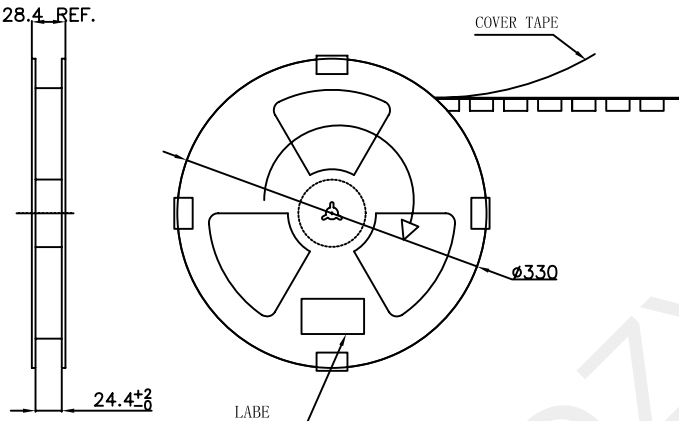
QTY/REEL	REEL/CARTON	QTY/CARTON
1000	10	10000

<图三>



<图二>

28.4 REF.



COVER TAPE PEELING FORCE: 50gf~150gf



NOTE:

1. 依<图一>示放置产品于下载中, 每穴放置1PCS产品.
2. 包装机包好后, 在REEL的个等分点贴上胶带, 以防止REEL张开, 每REEL贴1PCS标签, 如<图二>示
3. 包装数量见如<TABLE 1>示
4. 包装成箱见如<图三>示
箱底放防静电板, 再依次将指定数量的卷装产品用防水袋包好放入箱内, 四角分别放入四个三角护板, 最上层再放上防静电板.
5. 封箱, 在封好的纸箱上按客户要求写上料号, 数量等

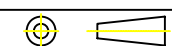


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TOLERANCE:

X.X ±0.30
X.XX ±0.25
X.XXX ±0.15

X.* ±2" X.X* ±0.5"



UNIT: mm [inch]

SCALE: 1:1 SIZE: A4

DRAWN BY:

陈一鸣

DATE:

2014-02-23

PART NAME:

包装图

CHECKED BY:

马跃

DATE:

2014-02-23

PART NO.

MOLD NO.

APPROVED BY:

邱敏

DATE:

2014-02-23

DRAW NO.

SHEET NO.

1 OF 1